DATE: June 15, 2023

产品规格书

SPECIFICATION FOR APPROVAL



	承	认	APPROVAL
工程部	品质	贡部	采购部
TECHNOLOGY DEPT.	QUALIT	Y DEPT.	PURCHASING DEPT.



深圳市炬烜科技有限公司

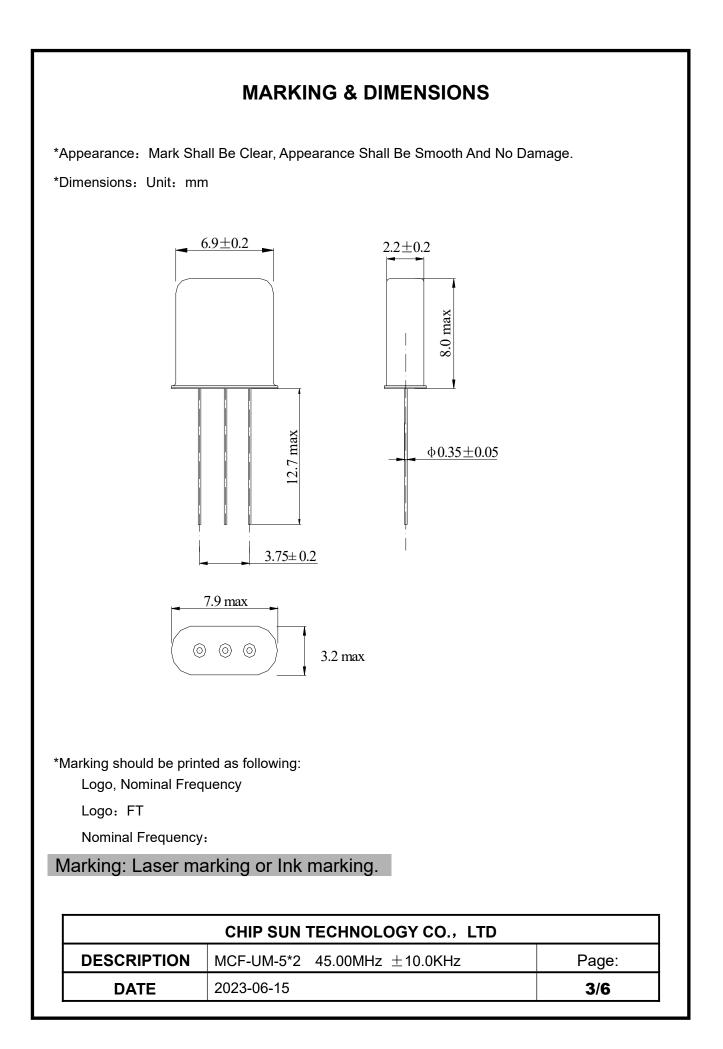
CHIP SUN TECHNOLOGY CO., LTD 地址 ADD: 深圳市龙华新区大浪腾龙路淘金地电子商务孵化基地 B 座 206 Rm. 206, Tower B, Taojindi Building, Tenglong Road, Dalang Street, Longhua New District, Shenzhen, China 电话 TEL: 86-755-83458798 传真 FAX: 86-755-83459818 网址 WEB ADD: http://www.chinachipsun.com E-MAIL: sales04@chinachipsun.com

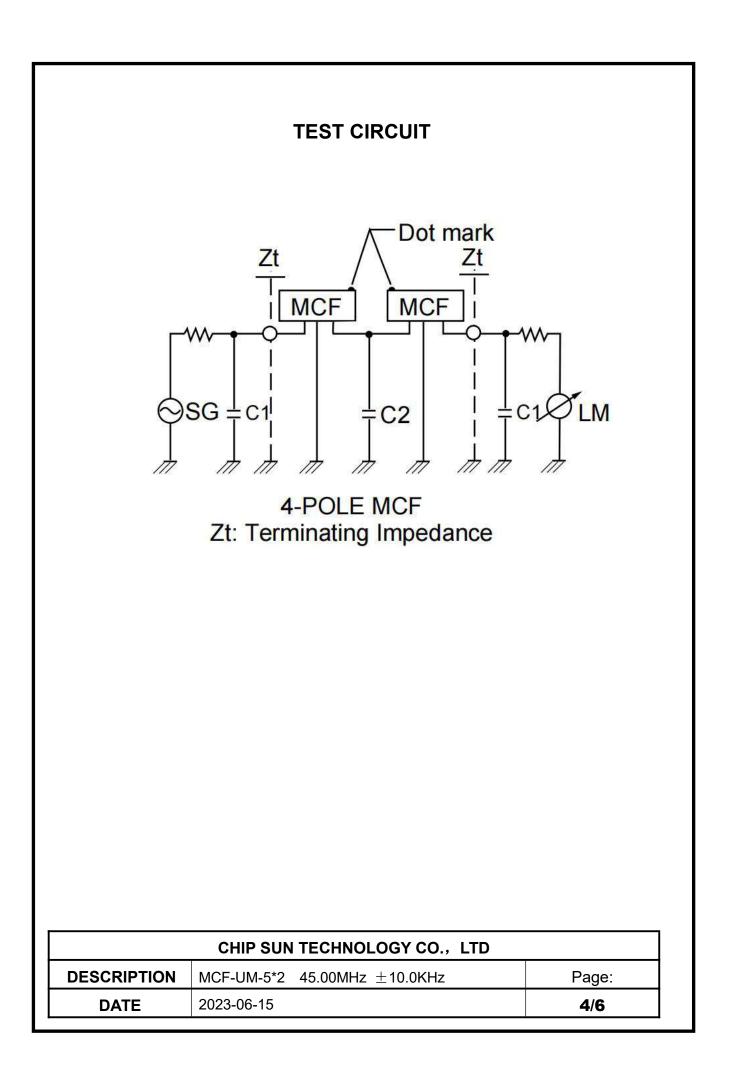
1. QUARTZ CRYSTAL UNIT SPECIFICATION

1. General

1.1 Model Name :	FT45M20B
1.2 Holder type :	UM-5*2
2. Electrical Specification :	
2.1 Frequency:	45.000MHz
2.2 Mode of Oscillation	AT Fundamental
2.3 Pass Band Width :	±10.0KHz min(at 3dB)
2.4 Stop Band Width:	±75KHz max(at 40dB)
2.5 Pass Band Ripple :	1.0dB max
2.6 Insertion Loss :	3.0dB max
2.7 Attenuation Guarantee :	90dB min (f0 \pm 910KHz)
2.8 Terminating Impedance :	IN: 910Ω//2.5pF
	OUT: 910Ω//2.5pF
	Coupling capacitance(C2): 5.0pF
2.9 Insulation resistance :	More than 500M ohms at DC 100V
3. Operable temperature range :	-20℃ To +70℃
4. Storage temperature range :	-40℃ To +85℃
4. Mechanical Data	
4.1 Sealing Test :	Reduced Pressure (260mmHg of mercury)
5. Dimensions and marking :	Refer to page. 3

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6.MECHANICAL/ENVIRONMENTAL CHARACTERISTICS

NO.	ITEM	SPECIFICATIONS
6.1	Resistance to Cold	The units should satisfy its frequency and resistance specifications stated in Table 1 after being subjected to stand at $-40\pm3^{\circ}$ C for 2 hours. The units are then allowed to stand at room temperature for approx 2 hours before checking.
6.2	Resistance to Heat	The units should satisfy its frequency and resistance specifications stated in Table 1 after being subjected to stand at $100\pm2^{\circ}C$ for 2 hours. The units are then allowed to stand at room temperature for approx 2 hours before checking.
6.3	Temperature Cycle	The units should satisfy its frequency and resistance specifications stated in Table 1 after the units are subjected to stand in a Low Temperature Chamber at $-40\pm3^{\circ}$ C for 30 minutes and to stand in a High Temperature Chamber at $100\pm2^{\circ}$ C for 30 minutes, with 2 to 3 minutes standby at room temperature in between the chamber transfers. This consist of one cycle; and units are subjected continuously for a cycles. After cycling, the units are allowed to stand at room temperature for approx 2 hours before checking.
6.4	Aging	The units should satisfy its frequency and resistance specifications stated in Table 1 after the units are subjected to stand 720 (30 days ± 12 hours in an 85 ± 3 °C chamber. The units are allowed to stand a room temperature approx 2 hours before checking.
6.5	Resistance to Damp	The units should satisfy its frequency and resistance specification stated in Table 1 after the units are subjected to stand in the tes chamber capable of maintaining 60±2°C temperature and 90 to 95%(RH) relative humidity for 500 hours. The units are then allowed to stand for approx 2 hours in room temperature before checking
6.6	Bending Strength of Lead Wire Termination	The unit's lead wire should withstand a weight of 450g in mass suspended from its original draw-out axis, and turning the body at a bending rate of 2 to 3 secs. until it IS approx 90° from the original axis; and returning back to its original position at the same bending rate. After this, the same method is repeated on the opposite 90° position There should be no abnormalities detected on the unit.

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6.7	Tensile Strength Termination	The units should withstand a tensile force applied to the termination in the direction of its draw-out axis of up to 900g maintained as is for 30±5 seconds. There should be no abnormalities detected on the unit.
6.8	Solder ability	Under JIS C 5033, at least 90% of the lead wire periphery surface is covered with new solder up to the point where it is dipped on a molten solder.
6.9	Resistance to Soldering Heat	The units are measured for its frequency and resistance in accordance with Table 1 after immersion into molten solder with a temperature of $350\pm10^{\circ}$ C for 3 to 4 seconds and at a depth up to a point 2.0 to 2.5 mm from the base root.
6.10	Dropping Test	 Unit Drop Test The units are measured for its frequency and resistance in accordance with Table 1 after allowing the units to fall freely from 20 cm of height 3 times on a firm wood . Shipping Carton Drop Test The units are measured for its frequency and resistance in accordance with Table 1 after dropping the units packaged inside a shipping carton box (randomly positioned) from a 50 cm height in each planar sides of the carton on a concrete floor.
6.11	Vibration Test	The units are measured for its frequency and resistance in accordance with Table 1 after subjecting to 2 hours of vibration with 1.5 mmp-p amplitude with 10-55-10Hz frequency sweep within 1 minute. Three perpendicular plane (axes) of vibration are available; however each unit is allowed to vibrate in only one plane, thus each plane requires approx 1/3 of the total units.

TABLE 1			
Electrical Specification	Should satisfy stated in 2.3 2.4 2.5 2.6		
	Should satisfy stated in 2.7 2.10		

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